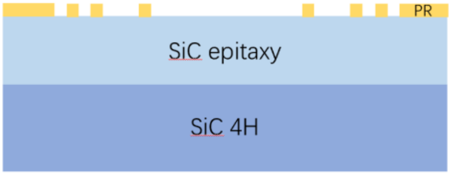
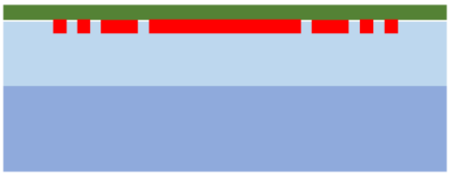
1. 保护环终端器件流程图

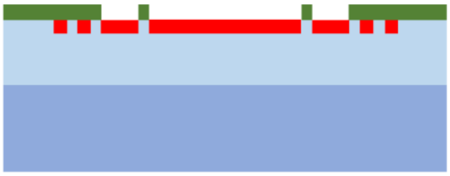


①刻蚀厚的光刻胶

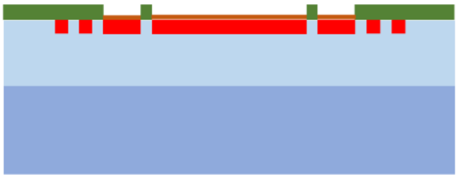
②离子注入



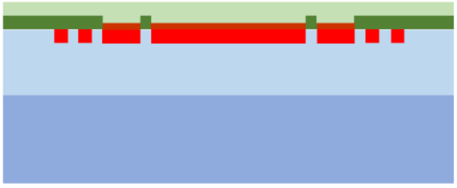
③沉积SiO2隔离层



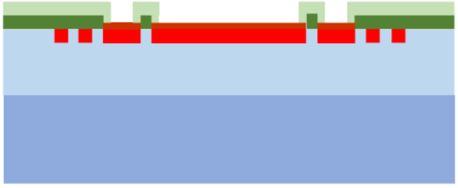
④刻蚀SiO2



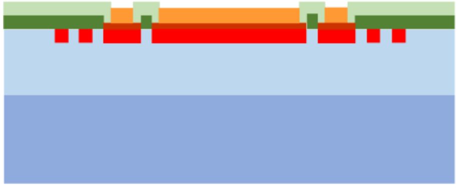
⑤溅射金属电极



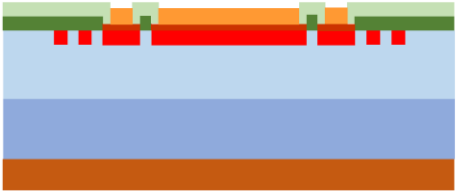
⑥沉积钝化层



⑦刻蚀钝化层

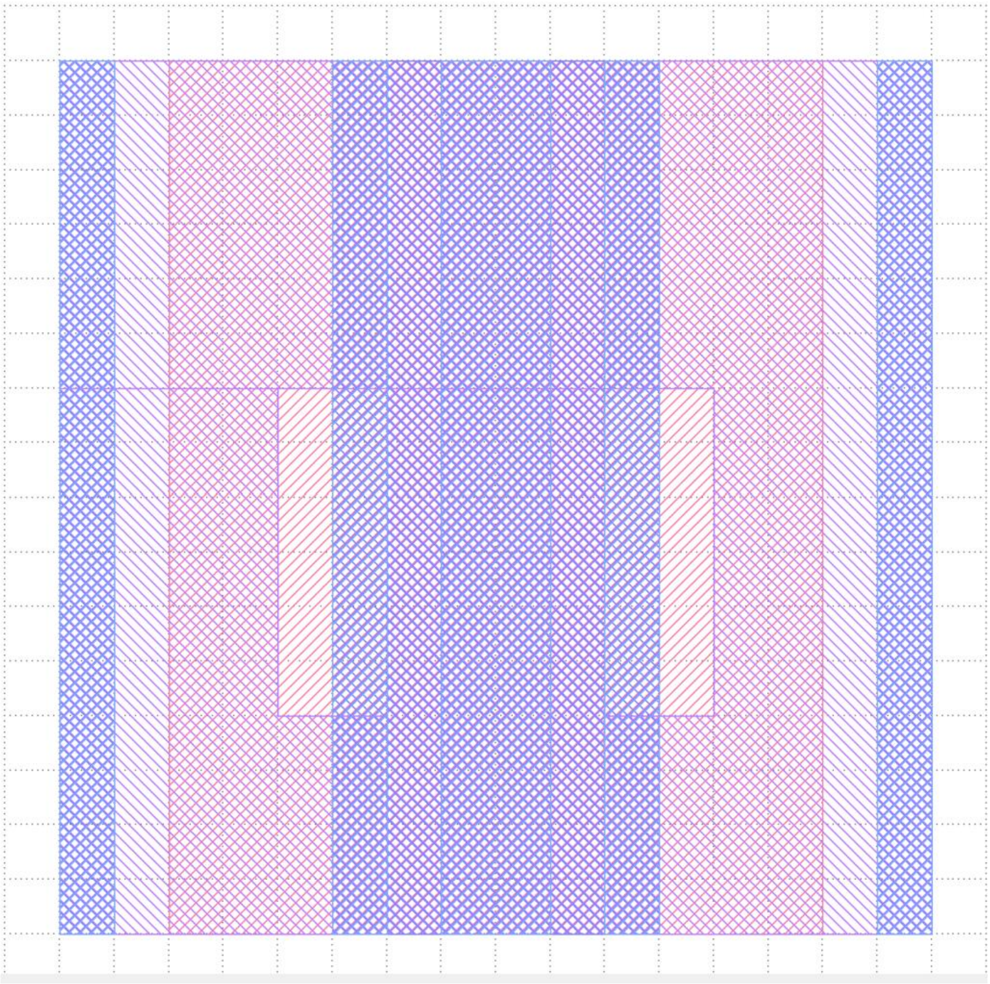


⑧沉积PAD金属+场板

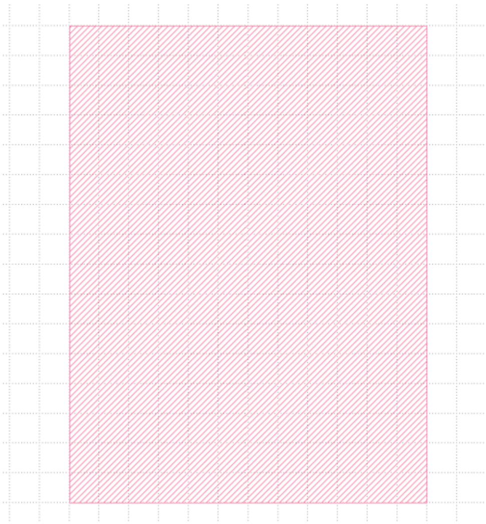


⑨衬底减薄+背底金属沉积

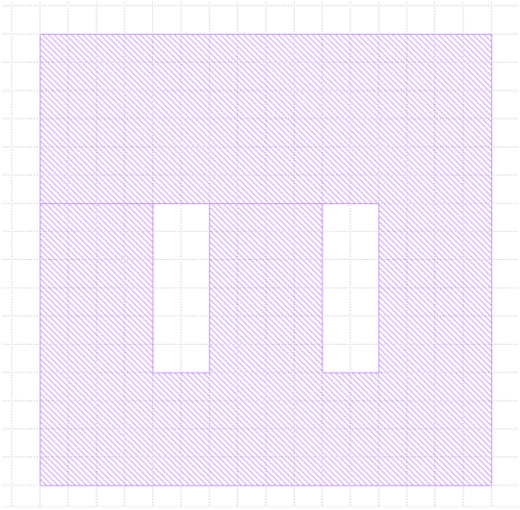
2. 刻蚀终端器件的光刻板



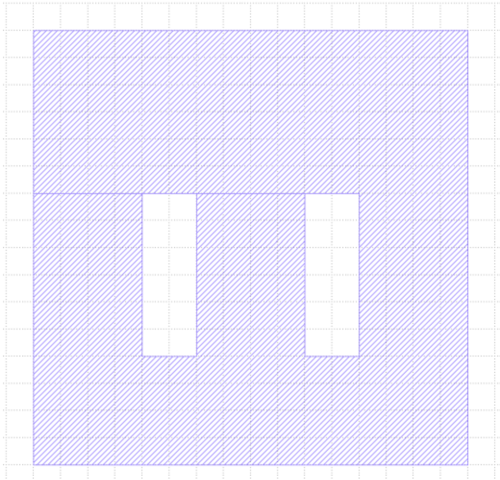
②过刻至增益层以下



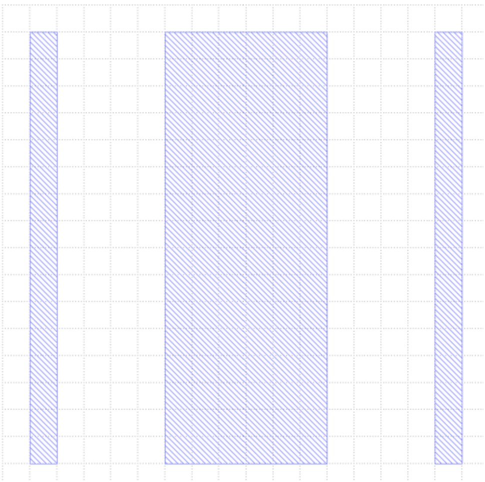
④刻蚀钝化层



⑤溅射金属电极



⑦刻蚀钝化层



⑧沉积 PAD 金属+场板